





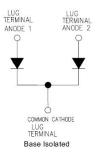
322CMQ030 SCHOTTKY RECTIFIER



Features

- 150℃ T_J operation
- · Center tap module
- High purity, high temperature epoxy encapsulation for
- enhanced mechanical strength and moisture resistance
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- · High current switching power supply
- Plating power supply
- Free-Wheeling diodes
- Reverse battery protection
- Converters
- UPS System
- Welding

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	-	30	V	
Average Rectified Forward Current	I _{F(AV)}	50% duty cycle @T _C =100°C, rectangular wave form	150(Per Leg)	A	
			300(Per Device)		
Peak One Cycle Non-Repetitive Surge Current (Per Leg)	I _{FSM}	8.3 ms, half Sine pulse	1800	Α	
Non-Repetitive Avalanche Energy(Peg Leg)	E _{AS}	T _J =25℃,I _{AS} =1A,L=30mH	270	mJ	
Repetitive Avalanche Current(Peg Leg)	I _{AR}	Current decaying linearly to zero in 1 µsec Frequency limited by T _J max. V _A =1.5×V _R typical	60	А	

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Electrical Characteristics:

Characteristics	Symbol	Condition	Тур.	Max.	Units
Forward Voltage Drop(Per Leg)*	V _{F1}	@ 150A, Pulse, T _J = 25 °C @ 300A, Pulse, T _J = 25 °C	0.46 -	0.56 0.70	V
	V _{F2}	@ 150A, Pulse, T _J = 125 °C @ 300A, Pulse, T _J = 125 °C	0.38 -	0.49 0.68	V
Reverse Current(Per Leg)*	I _{R1}	$@V_R = \text{rated } V_{R,} T_J = 25 ^{\circ}\text{C}$	0.5	10	mA
	I _{R2}	$@V_R = \text{rated } V_{R,} T_J = 125 ^{\circ}\text{C}$	500	650	mA
Junction Capacitance(Per leg)	Ст	$@V_R = 5V, T_C = 25 °C$ $f_{SIG} = 1MHz$	8700	11000	pF
Voltage Rate of Change	dv/dt	-	-	10,000	V/μs

^{*} Pulse width < 300 µs, duty cycle < 2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification		Units
Junction Temperature	TJ	-	-55 to +150		°C
Storage Temperature	T _{stg}	-	-55 to +150		°C
Typical Thermal Resistance Junction to Case(Per leg)	R ₀ JC	DC operation	0.50		°C/W
Typical Thermal Resistance Junction to Case(Per package)	R _θ Jc	DC operation	0.25		°C/W
Typical Thermal Resistance, case to Heat Sink	$R_{ heta cs}$	Mounting surface, smooth and greased	0.10		°C/W
Mounting Torque	T _M	-	Mounting Torque	24(min) 35(max)	Kg-cm
aag . eqae	- 141		Terminal Torque	35(min) 46(max)	1.5 0
Approximate Weight	wt	-	79		g
Case Style	PRM4 Isolated				

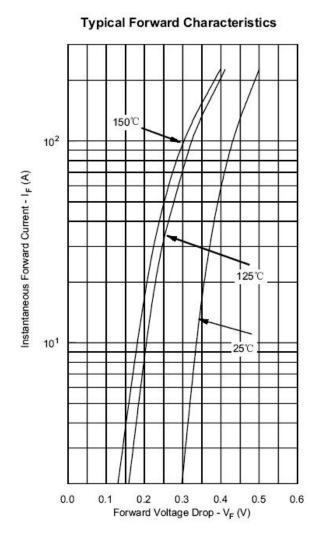
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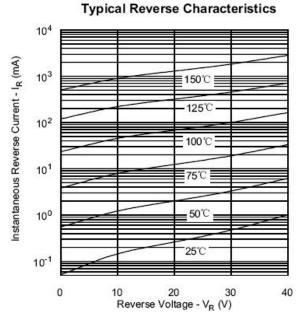


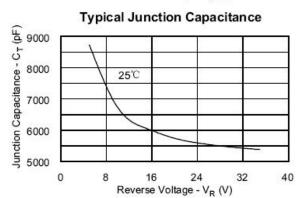




Ratings and Characteristics Curves







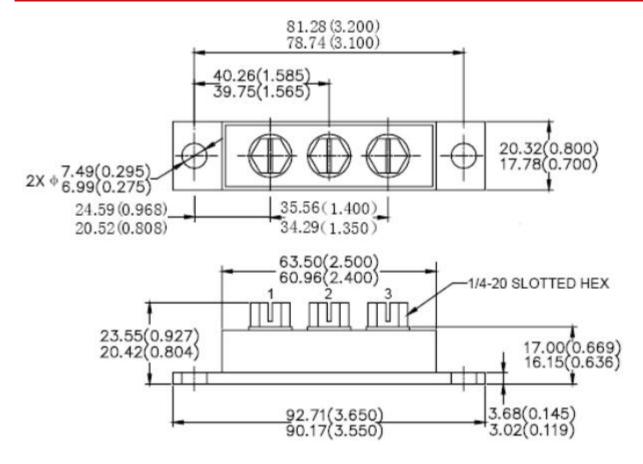
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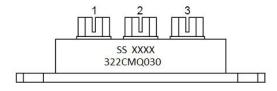


Mechanical Dimensions PRM4 Isolated(Millimeters/Inches)



Please Note: Anode 1 = Terminal 1; Anode 2 = Terminal 3; Common Cathode = Terminal 2 Suffix R Denotes for Reversed Polarity.

Marking Diagram



Where XXXX is YYWW

322CMQ030 = Part name SS = SS YY = Year WW = Week

Cautions: Molding resin

Epoxy resin UL:94V-0

Ordering Information

Device	Package	Shipping	
322CMQ030	PRM4 Isolated (Pb-Free)	9 pcs/box	

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

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